#### Introduction to CMOS VLSI Design

#### Lecture 17: Design for Testability

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Harvey Mudd College Spring 2004

## Outline

- Testing
  - Logic Verification
  - Silicon Debug
  - Manufacturing Test
- Fault Models
- Observability and Controllability
- Design for Test
  - Scan
  - BIST
- Boundary Scan

# Testing

□ Testing is one of the most expensive parts of chips

- Logic verification accounts for > 50% of design effort for many chips
- Debug time after fabrication has enormous opportunity cost
- Shipping defective parts can sink a company
- □ Example: Intel FDIV bug
  - Logic error not caught until > 1M units shipped
  - Recall cost \$450M (!!!)

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# **Logic Verification**

- Does the chip simulate correctly?
  - Usually done at HDL level
  - Verification engineers write test bench for HDL
    - Can't test all cases
    - Look for corner cases
    - Try to break logic design
- Ex: 32-bit adder
  - Test all combinations of corner cases as inputs:
    - 0, 1, 2, 2<sup>31</sup>-1, -1, -2<sup>31</sup>, a few random numbers

Good tests require ingenuity

# **Silicon Debug**

**Test the first chips back from fabrication** 

- If you are lucky, they work the first time
- If not...
- Logic bugs vs. electrical failures
  - Most chip failures are logic bugs from inadequate simulation
  - Some are electrical failures
    - Crosstalk
    - Dynamic nodes: leakage, charge sharing
    - Ratio failures
  - A few are tool or methodology failures (e.g. DRC)
  - Fix the bugs and fabricate a corrected chip

## **Shmoo Plots**

□ How to diagnose failures?

- Hard to access chips
  - Picoprobes
  - Electron beam
  - Laser voltage probing
  - Built-in self-test
- Shmoo plots
  - Vary voltage, frequency
  - Look for cause of electrical failures

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## **Shmoo Plots**

□ How to diagnose failures?

- Hard to access chips
  - Picoprobes
  - Electron beam
  - Laser voltage probing
  - Built-in self-test
- Shmoo plots
  - Vary voltage, frequency
  - Look for cause of electrical failures

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# **Manufacturing Test**

- □ A speck of dust on a wafer is sufficient to kill chip
- □ Yield of any chip is < 100%
  - Must test chips after manufacturing before delivery to customers to only ship good parts
- Manufacturing testers are very expensive
  - Minimize time on tester
  - Careful selection of test vectors



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# **Testing Your Chips**

□ If you don't have a multimillion dollar tester:

- Build a breadboard with LED's and switches
- Hook up a logic analyzer and pattern generator
- Or use a low-cost functional chip tester

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### **TestosterICs**

#### □ Ex: TestosterICs functional chip tester

- Designed by clinic teams and David Diaz at HMC
- Reads your IRSIM test vectors, applies them to your chip, and reports assertion failures



# **Stuck-At Faults**

- □ How does a chip fail?
  - Usually failures are shorts between two conductors or opens in a conductor
  - This can cause very complicated behavior
- A simpler model: *Stuck-At* 
  - Assume all failures cause nodes to be "stuck-at"
    0 or 1, i.e. shorted to GND or V<sub>DD</sub>
  - Not quite true, but works well in practice

#### **Examples**



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#### **Observability & Controllability**

- Observability: ease of observing a node by watching external output pins of the chip
- Controllability: ease of forcing a node to 0 or 1 by driving input pins of the chip
- Combinational logic is usually easy to observe and control
- Finite state machines can be very difficult, requiring many cycles to enter desired state
  - Especially if state transition diagram is not known to the test engineer

# **Test Pattern Generation**

- Manufacturing test ideally would check every node in the circuit to prove it is not stuck.
- Apply the smallest sequence of test vectors necessary to prove each node is not stuck.
- Good observability and controllability reduces number of test vectors required for manufacturing test.
  - Reduces the cost of testing
  - Motivates design-for-test







SA1 {0110} {1010} {0100}







 $A_3$ 

 $A_2$ 



#### Minimum set:

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SA1 {0110} {1010} {0100} {0110}







 $A_3$ 

 $A_2$ 

A<sub>1</sub>

- □ n3

#### Minimum set:

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#### Minimum set:

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SA0

{0110}

{0100}

SA1 {0110}  $A_3$  $A_2$ {1010} {0100} A<sub>1</sub> {0110}  $A_0$ {1110} **n1** {0110} n2 n3



Y

#### Minimum set:

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	SA1
A <sub>3</sub>	{0110}
$A_2$	{1010}
A <sub>1</sub>	{0100}
A <sub>0</sub>	{0110}
n1	{1110}
n2	{0110}
n3	{0101}
Y	





#### Minimum set:

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	SA1	SA0
$A_3$	{0110}	{1110}
$A_2$	{1010}	{1110}
$A_1$	{0100}	{0110}
$A_0$	{0110}	{0111}
n1	{1110}	{0110}
n2	{0110}	{0100}
n3	{0101}	{0110}
Y	{0110}	{1110}
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#### Minimum set: {0100, 0101, 0110, 0111, 1010, 1110}

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# **Design for Test**

- Design the chip to increase observability and controllability
- If each register could be observed and controlled, test problem reduces to testing combinational logic between registers.
- Better yet, logic blocks could enter test mode where they generate test patterns and report the results automatically.

#### Scan

- □ Convert each flip-flop to a scan register
  - Only costs one extra multiplexer
- Normal mode: flip-flops behave as usual
- Scan mode: flip-flops behave as shift register



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Slide 25

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SCAN

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## **Scannable Flip-flops**









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# **Built-in Self-test**

Built-in self-test lets blocks test themselves

- Generate pseudo-random inputs to comb. logic
- Combine outputs into a syndrome
- With high probability, block is fault-free if it produces the expected syndrome

Linear Feedback Shift Register

- Shift register with input taken from XOR of state
- Pseudo-Random Sequence Generator



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Linear Feedback Shift Register

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Linear Feedback Shift Register

- Shift register with input taken from XOR of state
- Pseudo-Random Sequence Generator



Step	Q
0	111
1	110
2	101
3	010
4	
5	
6	
7	

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Linear Feedback Shift Register

- Shift register with input taken from XOR of state
- Pseudo-Random Sequence Generator



Step	Q
0	111
1	110
2	101
3	010
4	100
5	
6	
7	

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Linear Feedback Shift Register

- Shift register with input taken from XOR of state
- Pseudo-Random Sequence Generator



Step	Q
0	111
1	110
2	101
3	010
4	100
5	001
6	
7	

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Linear Feedback Shift Register

- Shift register with input taken from XOR of state
- Pseudo-Random Sequence Generator



Step	Q
0	111
1	110
2	101
3	010
4	100
5	001
6	011
7	

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Linear Feedback Shift Register

- Shift register with input taken from XOR of state
- Pseudo-Random Sequence Generator



Step	Q
0	111
1	110
2	101
3	010
4	100
5	001
6	011
7	111 (repeats)

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### BILBO

#### Built-in Logic Block Observer

- Combine scan with PRSG & signature analysis



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# **Boundary Scan**

- Testing boards is also difficult
  - Need to verify solder joints are good
    - Drive a pin to 0, then to 1
    - Check that all connected pins get the values
- Through-hold boards used "bed of nails"
- SMT and BGA boards cannot easily contact pins
- Build capability of observing and controlling pins into each chip to make board test easier

# **Boundary Scan Example**



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# **Boundary Scan Interface**

- Boundary scan is accessed through five pins
  - TCK: test clock
  - TMS: test mode select
  - TDI: test data in
  - TDO: test data out
  - TRST\*: test reset (optional)
- Chips with internal scan chains can access the chains through boundary scan for unified test strategy.

#### Summary

- □ Think about testing from the beginning
  - Simulate as you go
  - Plan for test after fabrication
- "If you don't test it, it won't work! (Guaranteed)"

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